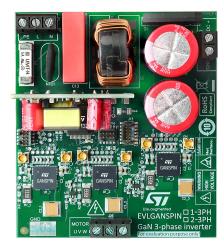


Data brief

# Three-phase 400 W motor control reference design with GANSPIN611 and STM32G431RB



#### **Features**

- Three-phase topology featuring the GANSPIN611 half-bridge system-inpackage
- GANSPIN611: 2x 138 m $\Omega$  650 V HEMT GaN + driver in 9x9 QFN with integrated LDOs, overcurrent and bootstrap diode
- STM32G431RB MCU Arm Cortex-M4 MCU 170 MHz
- 3-shunt topology for sensorless field-oriented control (FOC)
- 230 V AC mains line input filter and rectifier
- Typical power up to 400 W, 16 kHz
- Tuned at 10 V/ns dV/dt for EMI and motor reliability
- Interfaces: UART, Hall position sensors, SWD
- Three available supply rails at 12 V, 5 V, 3.3 V with VIPER06LS
- Shunt amplifiers with TSV911ILT 8 MHz operational amplifier
- Overcurrent protection



**Product status link** 

EVLGANSPIN1-3PH

### **Description**

The EVLGANSPIN1-3PH is a three-phase inverter based on the GANSPIN611 half-bridge GaN system-in-package (integrating 138 m $\Omega$  650 V e-mode HEMT GaN and the gate driver with LDOs, bootstrap diode, overcurrent protection) and the STM32G431RB with Arm Cortex®-M4 MCU at 170 MHz with 128 Kbytes of Flash memory, Math Accelerator.

The board can be used for sensorless field-oriented control (FOC), allowing driving permanent magnet synchronous motors (PMSMs) and brushless DC (BLDC) motors to cover a wide range of applications, such as refrigerator compressors, pumps, fans, and industrial appliances.

The EVLGANSPIN1-3PH is 77 x 88 mm wide, 4 layers, 2 Oz, FR-4 PCB, resulting in overall 12 °C/W  $R_{th(J-A)}$  (equivalent to 72°C/W for each GaN and 32 °C/W for each half-bridge) in still air.



## Safety and operating instructions







**HOT SURFACE** 



HIGH VOLTAGE

#### 1.1 General terms

Warning:

During assembly, testing, and operation, the evaluation board poses several inherent hazards, including bare wires, moving or rotating parts, and hot surfaces.

Danger:

There is a danger of serious personal injury, property damage, or death due to electrical shock and burn hazards if the kit or components are improperly used or installed incorrectly.

Danger:

The kit is not electrically isolated from the high-voltage supply AC/DC input. The evaluation board is directly linked to the mains voltage. No insulation is ensured between the accessible parts and the high voltage. All measuring equipment must use adequately insulated probes, clamps, and connecting wires; use adequate protective shields and use personal protective equipment.

Never touch the evaluation board while it is energized as it is capable of causing an electrical shock hazard. After supply disconnection, wait and ensure that the onboard capacitors are fully discharged before touching or working on the board.

Danger:

Board supplied with isolated AC source.

When using an oscilloscope with single ended probes or when connecting a PC to the board as for programming the  $\mu$ C with a standard programmer, the board AC input shall be provided from an isolated or floating AC source. Floating AC supply is required to avoid shorting AC mains to earth ground through oscilloscope or PC with the risk of death, injury, and equipment damage. However, touching a single high-voltage point of the board could still result in an electrical shock hazard, even when supplying the board with an AC isolated source, isolation transformer, or high-voltage DC source.

Danger:

Board supplied directly from AC mains grid.

When supplying the board directly from AC mains, the board ground is biased to the dangerous AC high voltage. It is mandatory, in this case, to use only specifically designed high voltage differential or isolated measuring and programming equipment, which are able to safely withstand high voltage. Touching any point of the board (included ground traces) can cause an electrical shock hazard.

Important:

All operations involving transportation, installation and use, and maintenance must be performed by skilled technical personnel able to understand and implement national accident prevention regulations. For the purposes of these basic safety instructions, "skilled technical personnel" are suitably qualified people who are familiar with the installation, use, and maintenance of power electronic systems.

#### 1.2 Intended use of evaluation board

The evaluation board is designed for demonstration purposes only, and must not be used for electrical installations or machinery. Technical data and information concerning the power supply conditions are detailed in the documentation and should be strictly observed.

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#### 1.3 Installing the evaluation board

- The installation and cooling of the evaluation board must be in accordance with the specifications and target application.
- The board must be protected against excessive strain. In particular, components should not be bent nor should isolating distances be altered during transportation or handling.
- No contact must be made with other electronic components and contacts.
- The board contains electrostatically sensitive components that are prone to damage if used incorrectly. Do not mechanically damage or destroy the electrical components (potential health risks).

#### Operating the evaluation board 1.4

To properly operate the board, follow these safety rules.

- 1. Work area safety:
  - The work area must be clean and tidy.
  - Do not work alone when boards are energized.
  - Protect against inadvertent access to the area where the board is energized using suitable barriers and
  - A system architecture that supplies power to the evaluation board must be equipped with additional control and protective devices in accordance with the applicable safety requirements (that is, compliance with technical equipment and accident prevention rules).
  - Use a non-conductive and stable work surface.
  - Use adequately insulated clamps and wires to attach measurement probes and instruments.

#### 2. Electrical safety:

- Remove the power supply from the board and electrical loads before taking any electrical measurements.
- Proceed with the arrangement of measurement setup, wiring, or configuration paying attention to highvoltage sections.
- Once the setup is complete, energize the board.

Danger: Do not touch the board when it is energized or immediately after it has been disconnected from the voltage supply as several parts and power terminals containing potentially energized capacitors need time to discharge.

> Do not touch the board after disconnection from the voltage supply as several parts, including the PCB, may still be very hot.

The kit is not electrically isolated from AC/DC input.

### 3. Personal safety

- Always wear suitable personal protective equipment such as insulating gloves and safety glasses.
- Take adequate precautions and install the board in such a way to prevent accidental touch. Use protective shields such as an insulating box with interlocks if necessary.

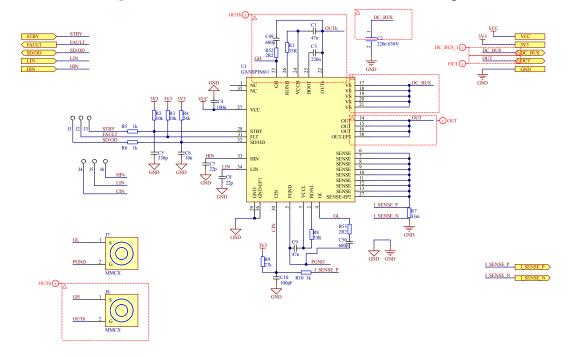
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## 2 Schematic diagrams

Figure 1. EVLGANSPIN1-3PH schematic - Hierarchical top connections

Figure 2. EVLGANSPIN1-3PH schematic - GANSPIN half bridge



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Figure 3. EVLGANSPIN1-3PH schematic - Supply

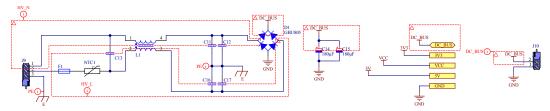


Figure 4. EVLGANSPIN1-3PH schematic - microcontroller

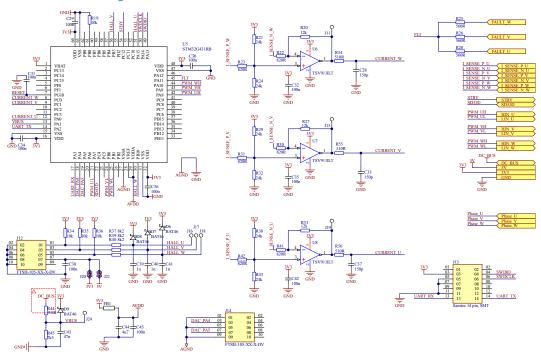
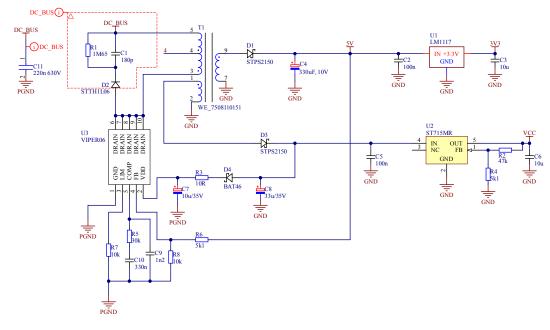


Figure 5. EVLGANSPIN1-3PH-PSU - Daughter board schematic



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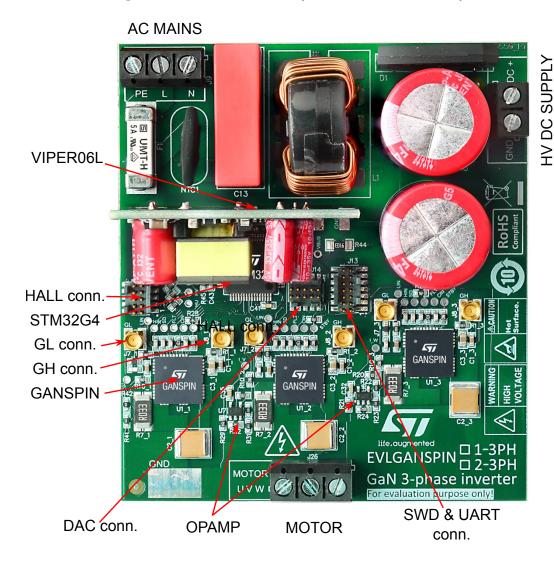
## 3 Board main connectors and key components

The board has been developed to demonstrate the use of the GANSPIN611 system-in-package to build a complete, HEMT GaN based, inverter for motor control.

The board can be directly supplied from the AC mains connector J4 or from a DC source from connector J6. The inverter maximum power strongly depends on several factors such as supply voltage, motor power factor, modulation index, and inverter switching frequency. The maximum output power could likely exceed 400 W depending on ambient temperature.

The main components and board connectors are shown in the following figures.

Figure 6. EVLGANSPIN1-3PH - top view connectors and components



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## 4 Bill of materials

Table 1. EVLGANSPIN1-3PH - main board bill of materials

Part reference	Part description	Part value	Package / Manufacturer' code
			Size 0603
C1_1, C1_2, C1_3, C9_1, C9_2, C9_3, C43	SMT ceramic capacitor	47 nF / 50 V / X7R	Würth Elektronik
_			885012206093
			Size 2220
C2_1, C2_2, C2_3	SMT ceramic capacitor	220 nF / 630 V / X7R	Würth Elektronik
			885342214142
			Size 0805
C3_1, C3_2, C3_3	SMT ceramic capacitor	220 nF / 25 V / X7R	Würth Elektronik
			885012207074
C4_1, C4_2, C4_3, C29,			Size 0603
C30, C31, C32, C34, C35,	SMT ceramic capacitor	100 nF / 25 V / X7R	Würth Elektronik
C36, C38, C42, C45			885012206071
			Size 0603
C5_1, C5_2, C5_3	SMT ceramic capacitor	330 pF / 50 V / NP0	Würth Elektronik
			885012006060
			Size 0603
C6_1, C6_2, C6_3	SMT ceramic capacitor	10 nF / 50 V / X7R	Würth Elektronik
			885012206089
			Size 0603
C7_1, C7_2, C7_3, C8_1, C8_2, C8_3	SMT ceramic capacitor	22 pF / 50 V / NP0	Würth Elektronik
00_2, 00_0			885012006053
			Size 0603
C10_1, C10_2, C10_3	SMT ceramic capacitor	100 pF / 50 V / NP0	Würth Elektronik
			885012206077
			Size 2220
C11, C12, C16, C17	SMT ceramic capacitor	4.7 nF / 250 V / Y2	Würth Elektronik
			8853522140011
			26.5 x 8.5 mm
C13	WCAP-FTXH film capacitor	330 nF / 310 V	Würth Elektronik
			890414026001CS
			Diam. 18, pitch 7.5 mm
C14, C15	Aluminum electrolytic capacitor	180 mF / 400 V	Würth Elektronik
			860021381024
			Size 0603
C28, C33, C37	SMT ceramic capacitor	150 pF / 50 V / X7R	Würth Elektronik
			885012206078
			Size 0603
C39, C40, C41	SMT ceramic capacitor	1 nF / 50 V / X7R	Würth Elektronik
			885012206083
C44	SMT ceramic capacitor	4.7 mF / 25 V / X5R	Size 0805

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Part reference	Part description	Part value	Package / Manufacturer' code
			Würth Elektronik
			885012107018
C49_1, C49_2, C49_3, C50_1, C50_2, C50_3	SMT ceramic capacitor	680 pF / 50 V / X7R	Size 0603 Würth Elektronik 885012206082
D1	8A glass passivated single- phase bridge rectifier	GBU805	GBU Taiwan Semiconductor
D6, D7, D8, D9	100V, 150mA small signal Schottky diode	BAT46	SOD-323 STMicroelectronics BAT46JFILM
F1	Surface mount fuse, Time-Lag T	5 A / 250 V slow	UMT250 Shurter 3403.0281.23
FB1	WE-CBF SMD EMI Suppression Ferrite Bead	100 R @ 100 MHz 500mA	Size 0603 Würth Elektronik 742792620
J7_1, J7_2, J7_3, J8_1, J8_2, J8_3	MMCX PCB SMT jack	-	MMCX_SMD Würth Elektronik 66012102111404
J9, J26	Connector terminal block T.H.	-	3 poles, pitch 5 mm Würth Elektronik 691502710003
J10	Connector terminal block T.H.	-	2 poles, pitch 5 mm Würth Elektronik 691502710002
J13	Connector header	-	7x2 poles, pitch 1.27 mm Samtec
J12, J14	Connector header	-	5x2 poles, pitch 1.27 mm Samtec
L1	Common mode power line choke	15 mH / 5 A / 38 mΩ	Würth Elektronik 7448040515
NTC1	NTC thermistor for inrush current limiting	2.2 Ω	Diam. 15, pitch 7.5 mm Epcos B57237S0229M000
R1_1, R1_2, R1_3, R8_1, R8_2, R8_3	SMT resistor	33 Ω	Size 0603
R2_1, R2_2, R2_3, R3_1, R3_2, R3_3, R19, R34, R35, R36	SMT resistor	10 kΩ	Size 0603
R5_1, R5_2, R5_3, R6_1, R6_2, R6_3, R10_1, R10_2, R10_3	SMT resistor	1 kΩ	Size 0603
R7_1, R7_2, R7_3	SMT resistor	33 mΩ / 2 W / 0.5%	Size 2512 Multicomp PRO MCLRP12DTWSR033

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Part reference	Part description	Part value	Package / Manufacturer' code
R9_1, R9_2, R9_3	SMT resistor	27 kΩ	Size 0603
R20, R27, R33	SMT resistor	12 kΩ	Size 0603
R4_1, R4_2, R4_3, R21, R24, R29, R32, R38, R43	SMT resistor	24 kΩ	Size 0603
R22, R23, R30, R31, R41, R42	SMT resistor	820 Ω	Size 0603
R25, R26, R28	SMT resistor	560 Ω	Size 0603
R37, R39, R40	SMT resistor	8.2 kΩ	Size 0603
			Size 1206
R44	SMT resistor	910 kΩ	Würth Elektronik
			560112132052
R45	SMT resistor	7.5 kΩ	Size 0603
R52_1, R52_2, R52_3, R53_1, R53_2, R53_3	SMT resistor	2.2 Ω	Size 0603
R54, R55, R56	SMT resistor	510 Ω	Size 0603
	600 V e-mode GaN high-power density half-bridge with high- voltage driver	GANSPIN611	QFN 9x9x 1 mm,
U1_1, U1_2, U1_3			35 leads, 0.6 mm pitch
			STMicroelectronics
U5	Mainstream Arm Cortex-M4 MCU 170 MHz	STM32G431RBT3	LQFP64 10 x 10 mm
00			STMicroelectronics
U6, U7, U8	Single Rail-to-Rail input/output 8	TSV911ILT	SOT23-5
00, 07, 08	MHz operational amplifiers	134911161	STMicroelectronics

Table 2. EVLGANSPIN1-3PH-PSU - Daughter board bill of materials

Part reference	Part description	Part value	Package / Manufacturer' code
C1	SMT ceramic capacitor	180 pF / 500 V / X7R	Size 1206
			Size 0805
C2, C5	SMT ceramic capacitor	100 nF / 16 V / X7R	Würth Elektronik
			885012207045
			Size 1206
C3, C6	SMT ceramic capacitor	10 mF / 25 V / X7R	Würth Elektronik
			885012208018
	Aluminum electrolytic capacitor	330 mF / 10 V	Diam. 8, pitch 3.5 mm
C4			Würth Elektronik
			860240274006
			Diam. 5, pitch 2 mm
C7	Aluminum electrolytic capacitors	10 mF / 35 V	Würth Elektronik
			860160572001
	Aluminum electrolytic capacitor	33 mF / 35 V	Diam. 5, pitch 2 mm
C8			Würth Elektronik
			860160572005
C9	SMT ceramic capacitor	1.2 nF / 25 V / X7R	Size 0603
C10	SMT ceramic capacitor	330 nF / 25 V / X7R	Size 0603
C10			Würth Elektronik

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Part reference	Part description	Part value	Package / Manufacturer' code
			885012206074
			Size 2220
C11	SMT ceramic capacitor	220 nF / 630 V / X7R	Würth Elektronik
			885342214142
			SMA
D1, D3	150 V, 2 A power Schottky rectifier	STPS2150	STMicroelectronics
			STPS2150A
			SMA
D2	Turbo 2 ultrafast high voltage rectifier	STTH1L06	STMicroelectronics
			STTH1L06A
			SOD-323
D4	100V, 150mA small signal Schottky diode	BAT46	STMicroelectronics
			BAT46JFILM
R1	SMT resistor	1.65 ΜΩ / 1%	Size 1206
R2	SMT resistor	47 kΩ / 1%	Size 0603
R3	SMT resistor	10 Ω / 1%	Size 0603
R4, R6	SMT resistor	5.1 kΩ / 1%	Size 0603
R5	SMT resistor	30 kΩ / 1%	Size 0603
R7, R8	SMT resistor	10 kΩ / 1%	Size 0603
T1	Transformer	4.5	Würth Elektronik
11	transformer	1.5 mH	7508110151
			SOT223
U1	Low drop fixed positive voltage regulator	LD1117 – 3.3V	STMicroelectronics
			LD1117AS33TR
	High input voltage, 85 mA LDO linear regulator	ST715	SOT23-5L
U2			STMicroelectronics
			ST715MR
			SSOP-10
U3	Energy saving high-voltage converter for direct feedback	VIPER06LS	STMicroelectronics
			VIPER06LS

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## Layout and component placements

Figure 7. Main board layout - top with component reference designators (top view)

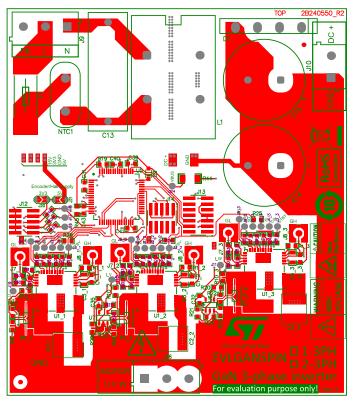
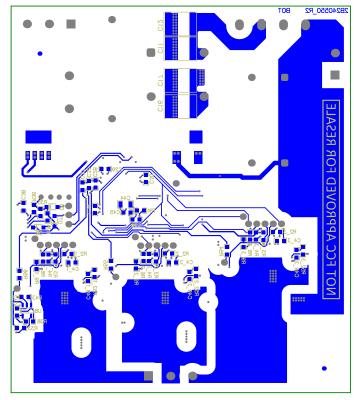


Figure 8. Main board layout - bottom with component reference designators (top view)



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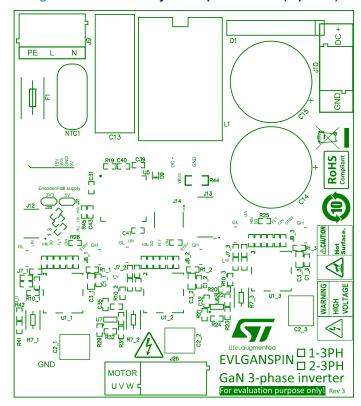
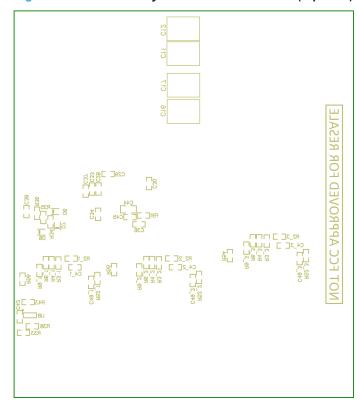


Figure 9. Main board layout - top silk screen (top view)

Figure 10. Main board layout - bottom silk screen (top view)



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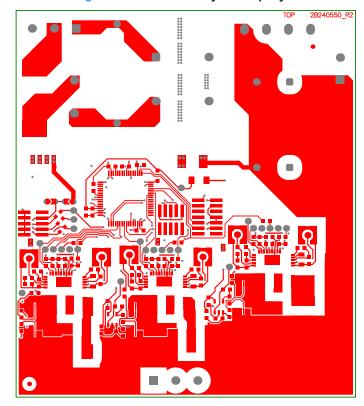
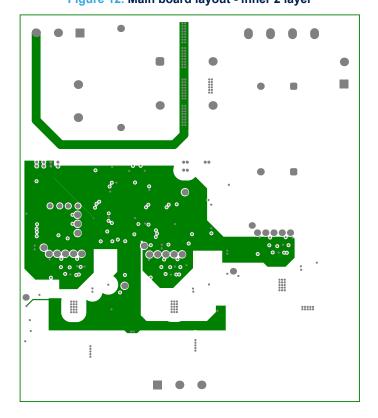


Figure 11. Main board layout - top layer

Figure 12. Main board layout - inner 2 layer



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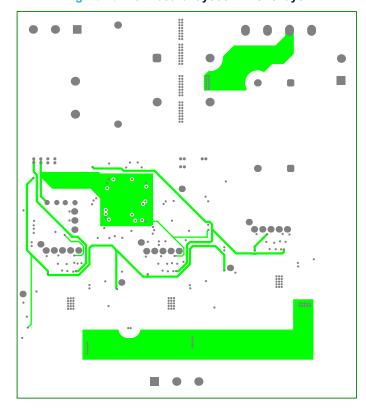
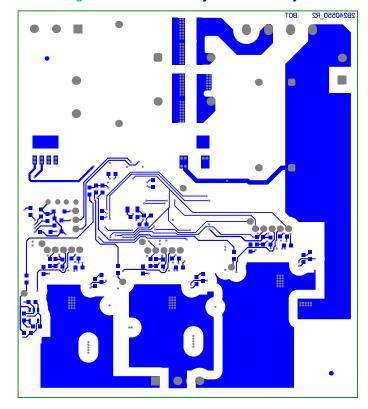


Figure 13. Main board layout - inner 3 layer

Figure 14. Main board layout - bottom layer



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U2 C5 D3 D3 Lite.augmented

Figure 15. PSU board layout - top with component reference designators (top view)

Figure 16. PSU board layout - top silk screen

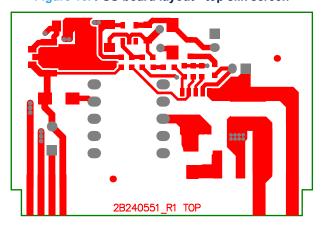
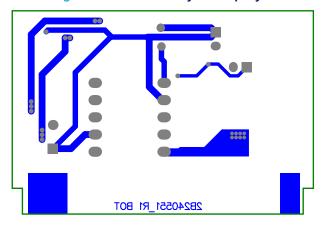


Figure 17. PSU board layout - top layer



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## **Revision history**

Table 3. Document revision history

Date	Version	Changes
26-Sep-2025	1	Initial release.

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